

OFFICIAL

OFFICIAL

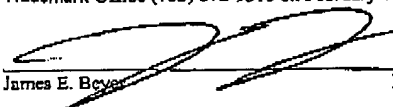
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicants : Salman Akram
Serial No. : 09/992,580
Filed : November 16, 2001
Title : **DIE STACKING SCHEME**
Docket No. : MIO 0072 VA
Examiner : N/A
Art Unit : 2815
Confirm. No. : 9954

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper is being facsimile transmitted to the Patent and Trademark Office (703) 872-9318 on February 14, 2002.


James E. Beyer

Reg. No. 39,564

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

PRELIMINARY AMENDMENT

In the Claims:

✓
Please ~~cancel~~ claims 19, 21, 22 and 45-51.

Please add new claims 52-56.

The entire set of presently pending claims has been reproduced below for the convenience of the Examiner. New claims and cancelled claims are indicated as such in the parenthetical following each claim number.

✓
19. (Cancelled)

20. A method of stacking a plurality of semiconductor die, said method comprising:
- providing a substrate;
 - providing a first semiconductor die including a pair of major surfaces, wherein
 - one of said pair of major surfaces of said first die defines a first active surface,

AY COPY RECEIVED

FEB 14 2002

TECHNOLOGY CENTER 2800